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APPLICATION NO.	F	ILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/782,838	•	02/23/2004	Isao Yokokawa	118749	5427
25944	7590	06/13/2005		EXAMINER	
OLIFF & F		GE, PLC	LUU, CHUONG A		
P.O. BOX 19928 ALEXANDRIA, VA 22320		22320		ART UNIT	PAPER NUMBER
	,			2818	
				DATE MAILED: 06/13/2005	

Please find below and/or attached an Office communication concerning this application or proceeding.

	Application No.	Applicant(s)
	10/782,838	YOKOKAWA ET AL.
Office Action Summary	Examiner	Art Unit
	Chuong A. Luu	2818
The MAILING DATE of this communication app Period for Reply	ears on the cover sheet with the c	orrespondence address
A SHORTENED STATUTORY PERIOD FOR REPLY THE MAILING DATE OF THIS COMMUNICATION. - Extensions of time may be available under the provisions of 37 CFR 1.13 after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above is less than thirty (30) days, a reply - If NO period for reply is specified above, the maximum statutory period w - Failure to reply within the set or extended period for reply will, by statute, Any reply received by the Office later than three months after the mailing earned patent term adjustment. See 37 CFR 1.704(b).	36(a). In no event, however, may a reply be time within the statutory minimum of thirty (30) days will apply and will expire SIX (6) MONTHS from cause the application to become ABANDONE	ely filed s will be considered timely. the mailing date of this communication. O (35 U.S.C. § 133).
Status		
Responsive to communication(s) filed on This action is FINAL . 2b)⊠ This Since this application is in condition for allowant closed in accordance with the practice under <i>E</i> .	action is non-final. nce except for formal matters, pro	
Disposition of Claims		
4) ⊠ Claim(s) 1-8 is/are pending in the application. 4a) Of the above claim(s) is/are withdraw 5) □ Claim(s) is/are allowed. 6) ⊠ Claim(s) 1-8 is/are rejected. 7) □ Claim(s) is/are objected to. 8) □ Claim(s) are subject to restriction and/or		
Application Papers		
9) The specification is objected to by the Examiner 10) The drawing(s) filed on is/are: a) access Applicant may not request that any objection to the of Replacement drawing sheet(s) including the correction of the oath or declaration is objected to by the Examiner	epted or b) objected to by the Edrawing(s) be held in abeyance. See on is required if the drawing(s) is objected	37 CFR 1.85(a). ected to. See 37 CFR 1.121(d).
Priority under 35 U.S.C. § 119		
 12) Acknowledgment is made of a claim for foreign a) All b) Some * c) None of: 1. Certified copies of the priority documents 2. Certified copies of the priority documents 3. Copies of the certified copies of the priority application from the International Bureau * See the attached detailed Office action for a list of 	s have been received. s have been received in Application ity documents have been received (PCT Rule 17.2(a)).	on No d in this National Stage
Attachment(s) 1) Notice of References Cited (PTO-892) 2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08) Paper No(s)/Mail Date 2/23/2004.	4) Interview Summary (Paper No(s)/Mail Dat 5) Notice of Informal Pa 6) Other:	e

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DETAILED ACTION

PRIOR ART REJECTIONS

Statutory Basis

Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

The Rejections

Claims 1-8 are rejected under 35 U.S.C. 103(a) as being unpatentable over Aga et al (U.S. 6,140,210) in view of Yamagata (U.S. 6,653,209 B1).

Aga discloses a method of fabricating an SOI wafer with

(1) a method of producing an SOI wafer in which an SOI layer is formed on a buried oxide film by, at least implanting at least one kind of ion of hydrogen ion and a rare gas ion into the surface portion of a bond wafer to form an ion-implanted layer, bonding the bond wafer and a base wafer to each other through an oxide film, and delaminating the resultant bonded wafer at the ion-implanted layer, wherein assuming that X (nm) represents the thickness of the buried oxide film and (nm) represents the thickness of the SOI layer in the SOI wafer immediately after delaminating at the ion-implanted layer, when forming the ion-implanted layer, the ion implantation is carried out with the ion implantation conditions being set such that the sum X + Y of the thickness of the buried oxide film and the thickness of the SOI layer satisfies X + Y > 1500 - 14X,

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after which the bonding process and the delaminating process are carried out and, thereafter, a thinning treatment of the SOI layer carried out to make the SOI layer into a thin film having a predetermined thickness (see column 4, lines 14-65 and column 6, lines 8-48. Figure 1);

- (2) wherein in forming the ion-implanted layer, the ion implantation is carried out with the ion implantation conditions being set such that the sum X+Y of the thickness of the buried oxide film and the thickness of the SOI layer becomes 390 nm or more when the thickness X of the buried oxide film is made into $80 \le X \ge 100$, such that X+Y becomes 810 nm or more when X is made into $50 \le X < 80$, and such that X + Y becomes 1090 nm or more when X is made into $30 \le X < 50$ (see column 6, lines 8-48. Figure 1);
- (3) wherein the thinning treatment of the SOI layer is carried out by a sacrificial oxidation treatment;
- (4) wherein the thinning treatment of the SOI layer is carried out by a sacrificial oxidation treatment;
- (5) an SOI wafer produced by the method of producing an SOI wafer (see Figure 1);
- (6) an SOI wafer produced by the method of producing an SOI wafer (see Figure 1);
- (7) an SOI wafer produced by the method of producing an SOI wafer (see Figure1);

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(8) an SOI wafer produced by the method of producing an SOI wafer (see Figure 1).

Aga teaches everything above except for the thickness X of the buried oxide film is $X \le 100$ nm. However, Yamagata discloses a method for forming a silicon thin film with (1)....the thickness X of the buried oxide film is $X \le 100$ nm (see column 6, lines 62-65). Therefore, it would have been obvious to one having ordinary skill in the art at the time the invention was made to modify the thickness X of the buried oxide film is $X \le 100$ of Aga's device (in accordance with the teaching of Yamagata) within the range as claimed for the purpose of providing for reduced power consumption and increase operational speed, and it also has been held that where the general conditions of a claim are disclosed in the prior ad, discovering the optimum or workable ranges involves only routine skill in the art and it is noted that the applicant does not disclose criticality in the ranges claimed. In re Aller, 105 USPQ 233 (see MPEP j 2144.05).

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Chuong A. Luu whose telephone number is (571) 272-1902. The examiner can normally be reached on M-F (6:15-2:45).

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, David C. Nelms can be reached on (571) 272-1787. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

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Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Chuong Anh Luu Patent Examiner June 8, 2005 Page 5